

AMENDMENTS TO THE CLAIMS

Sub 5. 1. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~
bond a magnetic head terminal comprising a metal pad having a bonding substance applied as a
surface finishing material, the surface finishing material being heat treated prior to bonding to a
surface.

2. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~
bond a magnetic head terminal as set forth in claim 1, wherein said bonding substance is solder.

3. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~
bond a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a
conductive polymer.

4. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~
bond a magnetic head terminal as set forth in claim 1, wherein said bonding substance is an
adhesive.

5. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~
bond a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a film.

6. (Currently Amended) A suspension bonding pad ~~for electrically bonding to electrically~~
bond a magnetic head terminal as set forth in claim 2, wherein a bump height for the solder is
approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .

7. (Currently Amended) A disk drive suspension comprising:
a bonding pad for electrically bonding a magnetic head terminal, wherein said bonding
pad includes a metal pad having a bonding substance applied as a surface finishing material, the
surface finishing material being heat treated prior to bonding to a surface.

8. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 7, wherein
said bonding substance is solder.

9. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 7, wherein
said bonding substance is a conductive polymer.

10. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 7, wherein
said bonding substance is an adhesive.

11. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 7, wherein
said bonding substance is a film.

12. (Currently Amended) The disk drive suspension as ~~claim~~ set forth in claim 8, wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .
